

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	automold\$4	JPO	OR	ON	2006/06/14 09:24
L2	78	(mold\$4 mould\$4) and laser and resist	JPO	OR	ON	2006/06/14 09:27
L3	0	(mold\$4 mould\$4) and laser and resist and encapsulat\$4	JPO	OR	ON	2006/06/14 09:25
L4	0	(mold\$4 mould\$4) and laser and resist and ablat\$4	JPO	OR	ON	2006/06/14 09:27
L5	32	(mold\$4 mould\$4) and laser and resist and remov\$4	JPO	OR	ON	2006/06/14 09:27
L6	25	(mold\$4 mould\$4) and laser and resist with remov\$4	JPO	OR	ON	2006/06/14 09:27
L7	6	(mold\$4 mould\$4) and laser with resist with remov\$4	JPO	OR	ON	2006/06/14 09:36
L8	2	((("5635671") or ("6221690")).PN.	USPAT; USOCR	OR	OFF	2006/06/14 11:00
L9	139	(mold\$4 mould\$4) and laser with (nd yag nd:yag ndyag excimer)	JPO	OR	ON	2006/06/14 09:37
L10	13	(mold\$4 mould\$4) and laser with (nd yag nd:yag ndyag excimer) with remov\$4	JPO	OR	ON	2006/06/14 09:40
L11	0	(mold\$4 mould\$4) and laser with (nd yag nd:yag ndyag excimer) with remov\$4 and encapsulat\$4	JPO	OR	ON	2006/06/14 09:40
L12	0	(mold\$4 mould\$4) and laser with (nd yag nd:yag ndyag excimer) and encapsulat\$4	JPO	OR	ON	2006/06/14 09:40
L13	13	laser with (nd yag nd:yag ndyag excimer) and encapsulat\$4	JPO	OR	ON	2006/06/14 09:49
L14	2	(laser with (clean\$4 remov\$4 ablat\$4)) and ((encapsulat\$4 mold\$4 mould\$4) with subsequent\$4)	JPO	OR	ON	2006/06/14 09:52
L15	293	((clean\$4 remov\$4 ablat\$4)) and (subsequent\$4 adj7 (encapsulat\$4 mold\$4 mould\$4))	JPO	OR	ON	2006/06/14 09:53
L16	0	(laser with (clean\$4 remov\$4 ablat\$4)) and (subsequent\$4 adj7 (encapsulat\$4 mold\$4 mould\$4))	JPO	OR	ON	2006/06/14 10:10
L17	1980	(laser with (clean\$4 remov\$4 ablat\$4)) and (after\$5 near\$7 (encapsulat\$4 mold\$4 mould\$4))	JPO	OR	ON	2006/06/14 10:11
L18	47	(laser with (clean\$4 remov\$4 ablat\$4)) and (after\$5 with (encapsulat\$4 mold\$4 mould\$4))	JPO	OR	ON	2006/06/14 10:17

## EAST Search History

L19	410	(laser with (clean\$4 remov\$4 ablat\$4) with resin)	JPO	OR	ON	2006/06/14 10:17
L20	69	(laser with (clean\$4 remov\$4 ablat\$4) with resin) and (mold\$4 encapsulat\$4)	JPO	OR	ON	2006/06/14 10:20
L21	2	(laser with (clean\$4 remov\$4 ablat\$4) with resin) and (subsequent\$4 with (mold\$4 encapsulat\$4))	JPO	OR	ON	2006/06/14 10:18
L22	77	(laser with (clean\$4 remov\$4 ablat\$4) with (resist resin)) and (mold\$4 encapsulat\$4)	JPO	OR	ON	2006/06/14 10:21
L23	47	(laser with (clean\$4 remov\$4 ablat\$4) with (resist resin)) and ((mold\$4 encapsulat\$4) with (clean\$4 remov\$4 ablat\$4))	JPO	OR	ON	2006/06/14 10:36
L24	2	23 not 20	JPO	OR	ON	2006/06/14 10:37
L25	0	vision with system and (detect\$4 with resist)	JPO	OR	ON	2006/06/14 10:37
L26	24	vision with system and (detect\$4 with resist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:38
L27	4	vision with system same (detect\$4 with resist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:40
L28	57	((visual\$4 vision) with detect\$4 with resist) not 27	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:41
L29	0	((visual\$4 vision) with detect\$4 with resist) not 27 and ((mold\$4 mould\$4) with semiconduct\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:41
L30	29	((visual\$4 vision) with detect\$4 with resist) not 27 and semiconduct\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:41
L32	8	((visual\$4 vision) with detect\$4 with resist) same semiconduct\$4 not 27	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:52

## EAST Search History

L33	11	((("4987286") or ("5023424") or ("5495126") or ("5634230") or ("5950071") or ("6566169") or ("4904498") or ("5852870") or ("5928533") or ("6281090") or ("6866910"))).PN.	USPAT; USOCR	OR	OFF	2006/06/14 10:52
L34	4	"20040209376" "20020089058"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:53
L35	15	33 34	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:53
L36	2	35 and laser with (resist resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:54
L37	1	("5364493").PN.	USPAT; USOCR	OR	OFF	2006/06/14 11:01
L38	3	8 37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:02
L39	3	38 and laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:02
L40	2	38 and laser with remov\$4 with (resist resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:14
L41	0	38 and laser with remov\$4 with (resist resin) same (mold\$4 mould\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:03
L42	688	semiconductor with (mold\$4 automold\$4) with laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:15

## EAST Search History

L43	203	semiconductor with (mold\$4 automold\$4) with laser with (encapsulat\$4 seal\$4 packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:15
L44	33	semiconductor with (mold\$4 automold\$4) with laser with (encapsulat\$4 seal\$4 packag\$4) with (remov\$4 etch\$4 ablat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:16
L45	1	semiconductor with (automold\$4) with laser with (encapsulat\$4 seal\$4 packag\$4) with (remov\$4 etch\$4 ablat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:18
L46	1	semiconductor with (automold\$4) with laser with (encapsulat\$4 seal\$4 packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:17
L47	2	semiconductor with (automold\$4) with laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:17
L48	2	(automold\$4) with laser with (encapsulat\$4 seal\$4 packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:17
L49	9	(automold\$4) with laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:17
L50	259	semiconductor with laser with (encapsulat\$4 seal\$4 packag\$4) with (remov\$4 etch\$4 ablat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:18
L51	41	semiconductor with laser with (encapsulat\$4 seal\$4 packag\$4) with (remov\$4 etch\$4 ablat\$4) with (mold\$4 mould\$4 injection)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:19
L52	33	automold\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:24

## EAST Search History

L53	9	automold\$4 with semiconduct\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:21
L54	1	("5352107").PN.	USPAT; USOCR	OR	OFF	2006/06/14 11:21
L55	0	54 and laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:21
L56	0	54 and (uv ultraviolet infrared ir heat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:22
L57	18	52 and laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:28
L58	6	52 and laser and vision	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:28
L59	0	52 and laser and (visual\$4 camera)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:29
L60	0	52 and laser and video\$9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:29
L61	14	52 and laser and view\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:39
L62	3	((("5352107") or ("6465743") or ("3767304")).PN.	USPAT; USOCR	OR	OFF	2006/06/14 11:39
L63	0	62 and (nd yag ndyag excimer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:39

## EAST Search History

S1	16	((("5607601") or ("6587009") or ("3866398") or ("4752668") or ("4894115") or ("5104480") or ("5147680") or ("5442416") or ("6242079") or ("6245677") or ("6376290") or ("6537743") or ("6550989") or ("5950071") or ("4746390") or ("6670222"))).PN.	USPAT; USOCR	OR	OFF	2006/06/14 09:23
S2	2	"20030003688"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 12:50
S3	18	S1 S2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 12:51
S4	1207	resist with laser with remov\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 12:52
S5	31	S4 and (bga "ball grid" "ball-grid")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 12:53
S6	16	S5 and (nd yag ndyag excimer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 13:14
S7	10	S3 and (nd yag ndyag excimer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 13:14
S8	3	S4 and S7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:21
S9	7	S7 not S8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:09

## EAST Search History

S10	0	(photoresist photolithograph\$4) with (wafer semiconduct\$4) with automold\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:10
S11	5	(photoresist photolithograph\$4) same (wafer semiconduct\$4) same automold\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:11
S12	31	automold\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:11
S13	23	S12 and (silicon semiconduct\$5 wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:11
S14	16	S12 and laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:25
S15	6	S14 and (nd yag ndyag excimer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:27
S16	10	S14 not S15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:39
S17	4	S16 and degat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:47
S18	0	S16 and vision	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:48
S19	5	S12 and vision	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:48

## EAST Search History

S20	10	S4 and vision	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:51
S21	1	("6025256").PN.	USPAT; USOCR	OR	OFF	2005/09/13 14:52
S22	0	S21 and vision	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:52